

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (cancelled)

2. (currently amended) A lead-free solder used to connect a connection lead to a material, comprising:

an alloy composition containing 0.002 to 0.015% by mass of phosphorus with the balance consisting of tin;

wherein bismuth, antimony, [and] gallium and titanium are not added to said alloy composition.

3. (cancelled)

4. (currently amended) A connection lead comprising:

a copper strip or other strip conductor; and

a plating provided on at least one side of the strip conductor, said plating being formed of a lead-free solder composed mainly of tin,

said plating containing 0.002 to 0.015% by mass of phosphorus with the balance consisting of tin, and having a shape such that the plating in a widthwise direction of the strip conductor has a bulge as viewed in section with an apex being located at a proper position in the widthwise direction of the strip conductor, and

wherein bismuth, antimony, [and] gallium and titanium are not added to said plating.

5. (original) The connection lead according to claim 4, wherein the bulge is in the form of an arc, a triangle, or stairs of which the apex is located at a proper position in the widthwise direction of the strip conductor.

6. (cancelled)

7. (previously presented) The connection lead according to claim 4, wherein the strip connector on its both sides is exposed or is covered with the lead-free solder constituting the plating.

8-13. (cancelled)

14. (previously presented) The lead free solder according to claim 2, wherein:

the alloy composition further containing 2.0 to 5.0% by mass of silver and 0.01 to 2.0% by mass of copper.

15. (currently amended) An alloy composition for a lead free solder used to connect a connection lead to a material, comprising:

0.002 to 0.015% by mass of phosphorus; and

tin;

wherein bismuth, antimony, [and] gallium and titanium are not added to said alloy composition.

16. (previously presented) The alloy composition according to claim 15, wherein the tin forms the balance of the composition.

17. (previously presented) An alloy composition for a lead free solder used to connect a connection lead to a material, consisting of:

0.002 to 0.015% by mass of phosphorus;

2.0 to 5.0 % by mass of silver;

0.01 to 2.0% by mass of copper; and

tin.

18. (previously presented) The connection lead according to claim 4, wherein said plating further containing 2.0 to 5.0% by mass of silver and 0.01 to 2.0% by mass of copper.

19. (previously presented) The alloy composition according to claim 15, further comprising:

2.0 to 5.0% by mass of silver; and

0.01 to 2.0% by mass of copper.

20. (currently amended) The lead free solder according to claim 2, wherein said alloy composition excludes bismuth, antimony₁ [and] gallium and titanium.

21. (currently amended) The connection lead according to claim 4, wherein said plating excludes bismuth, antimony₁ [and] gallium and titanium.

22. (currently amended) The alloy composition according to claim 15, wherein said alloy composition excludes bismuth, antimony, [and] gallium and titanium.

23. (cancelled)